

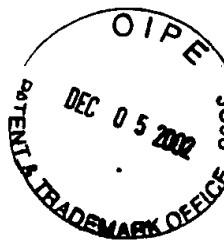
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Kenji ITOH et al.

Serial No. 09/412,510

Filed: October 5, 1999

For: PROCESS FOR TREATING A
SUBSTRATE WITH A PLASMA

Group Art Unit: 1762

Examiner: M. Padgett

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AMENDMENTCommissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated July 5, 2002, please amend the above-identified application as follows.

IN THE CLAIMS:

Please cancel claims 20-39 without prejudice or disclaimer to the subject matter recited therein.

Please add new claims 42-72 as follows:

~~-42.~~ (New) A process comprising the steps of:

providing first and second electrodes opposed to each other in a reaction chamber, said first electrode having at least one inlet having an opening elongated in a first direction;

introducing an etching gas through said at least one inlet into said reaction chamber;

generating a plasma of said etching gas by applying a voltage between said first and second electrodes wherein at each said at least one inlet said plasma extends from the